

SOLVENTLESS THERMOSETTING PHOTOSENSITIVE VIA-FILLING MATERIAL

ABSTRACT OF THE DISCLOSURE

A via-filling material improves a via-filling process in manufacturing multi-layered printed circuit boards. The via-filling material is capable of undergoing UV pre-cure and thermal post-cure step. Exposed to ultraviolet light, the via-filling material filled up the two ends of the via form solid barrier films so that the inside via-filling material will not flow out during a thermal post curing process due to an lower viscosity of said material. The dual-cure treatment resolves the problems of polishing, sagging and bubbling in the via-filling process and ensures the integrity of the filling material. As a result, the via-filling material with smooth surface and a solid inside without void or hole therein formed.